

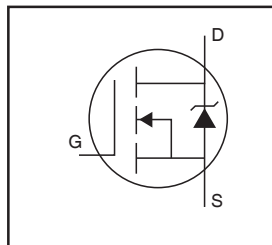
Features

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dt Rating
- 150°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to T_{jmax}
- Lead-Free, RoHS Compliant
- Automotive Qualified *

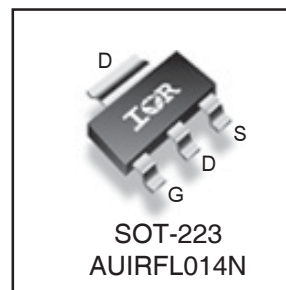
Description

Specifically designed for Automotive applications, this Cellular design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.

HEXFET® Power MOSFET



$V_{(BR)DSS}$	55V
$R_{DS(on)}$ max.	0.16Ω
I_D	1.9A



G	D	S
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRFL014N	SOT-223	Tube	95	AUIRFL014N
		Tape and Reel	2500	AUIRFL014NTR

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I_D @ $T_A = 25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V ^⑥	2.7	A
I_D @ $T_A = 25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V ^⑤	1.9	
I_D @ $T_A = 70^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V ^⑤	1.5	
I_{DM}	Pulsed Drain Current ^①	15	
P_D @ $T_A = 25^\circ\text{C}$	Power Dissipation (PCB Mount) ^⑥	2.1	W
P_D @ $T_A = 25^\circ\text{C}$	Power Dissipation (PCB Mount) ^⑤	1.0	W
	Linear Derating Factor (PCB Mount) ^⑤	8.3	W/°C
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy ^②	48	mJ
I_{AR}	Avalanche Current ^①	1.7	A
E_{AR}	Repetitive Avalanche Energy ^{①⑤}	0.1	mJ
dv/dt	Peak Diode Recovery dv/dt ^③	5.0	V/ns
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state) ^⑤	90	120	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB mount, steady state) ^⑥	50	60	

HEXFET® is a registered trademark of International Rectifier.

*Qualification standards can be found at <http://www.irf.com/>

Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

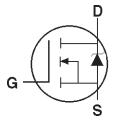
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	55	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.054	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D = 1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.16	Ω	$V_{GS} = 10V, I_D = 1.9A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
g_{fs}	Forward Transconductance	1.6	—	—	S	$V_{DS} = 25V, I_D = 0.85A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	$V_{DS} = 44V, V_{GS} = 0V$
		—	—	25		$V_{DS} = 44V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$

Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Q_g	Total Gate Charge	—	7.0	11	nC	$I_D = 1.7A$
Q_{gs}	Gate-to-Source Charge	—	1.2	1.8		$V_{DS} = 44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	3.3	5.0		$V_{GS} = 10V$, See Fig 6 and 9 ④
$t_{d(on)}$	Turn-On Delay Time	—	6.6	—	ns	$V_{DD} = 28V$
t_r	Rise Time	—	7.1	—		$I_D = 1.7A$
$t_{d(off)}$	Turn-Off Delay Time	—	12	—		$R_G = 6.0\Omega$
t_f	Fall Time	—	3.3	—		$R_D = 16\Omega$, See Fig.10 ④
C_{iss}	Input Capacitance	—	190	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	72	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	33	—		$f = 1.0\text{MHz}$, See Fig.5

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	1.3	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	15		
V_{SD}	Diode Forward Voltage	—	—	1.0	V	$T_J = 25^\circ\text{C}, I_S = 1.7A, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	41	61	ns	$T_J = 25^\circ\text{C}, I_F = 1.7A$
Q_{rr}	Reverse Recovery Charge	—	64	95	nC	$di/dt = 100A/\mu s$ ④


Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- ② $V_{DD} = 25V$, starting $T_J = 25^\circ\text{C}$, $L = 8.2\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 3.4A$. (See Figure 12)
- ③ $I_{SD} \leq 1.7A$, $di/dt \leq 250A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 150^\circ\text{C}$
- ④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.
- ⑤ When mounted on FR-4 board using minimum recommended footprint.
- ⑥ When mounted on 1 inch square copper board, for comparison with other SMD devices.

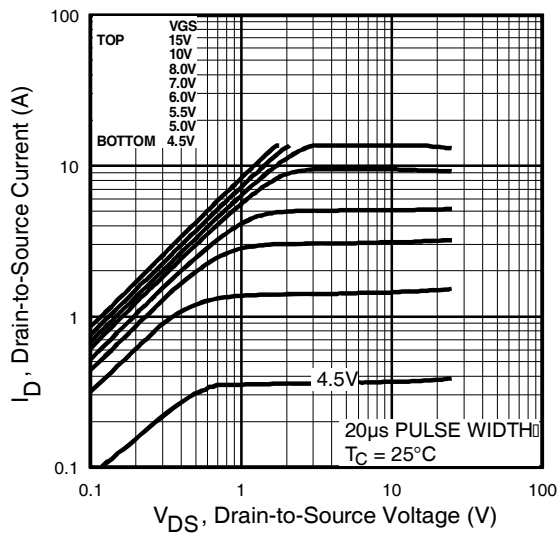


Fig 1. Typical Output Characteristics

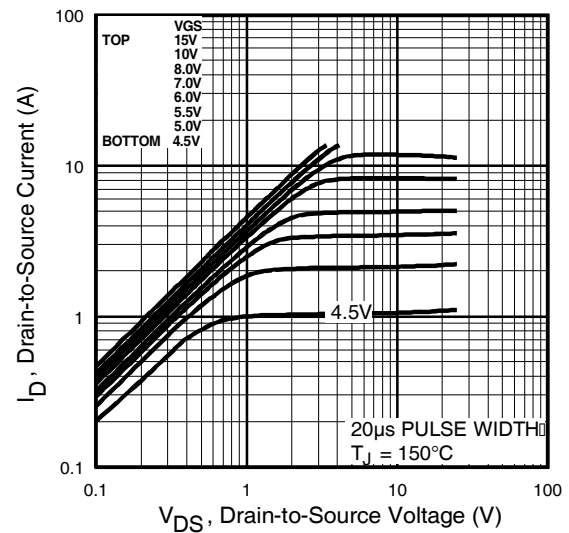


Fig 2. Typical Output Characteristics

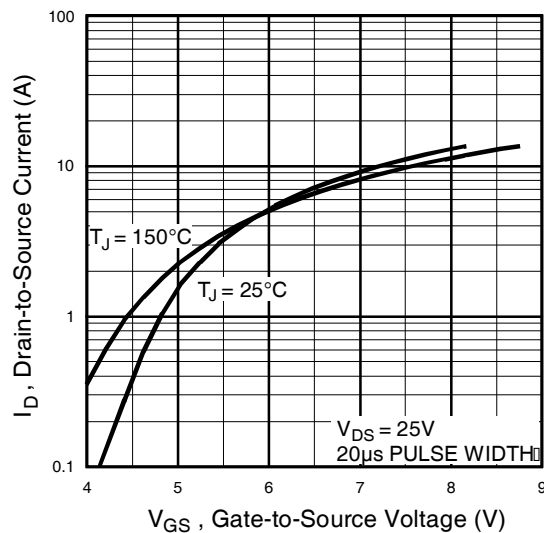


Fig 3. Typical Transfer Characteristics

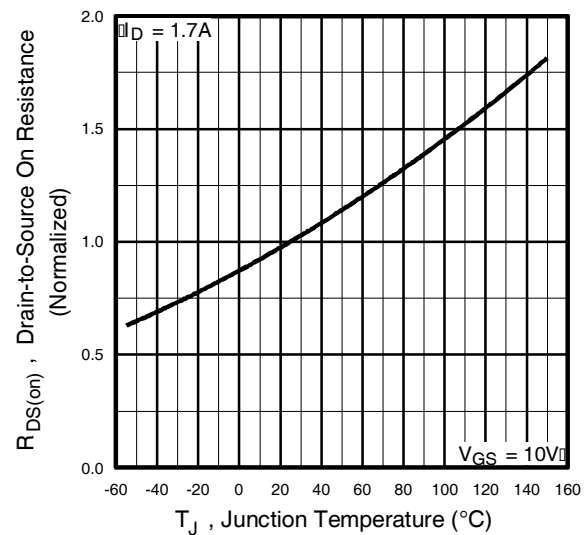


Fig 4. Normalized On-Resistance Vs. Temperature

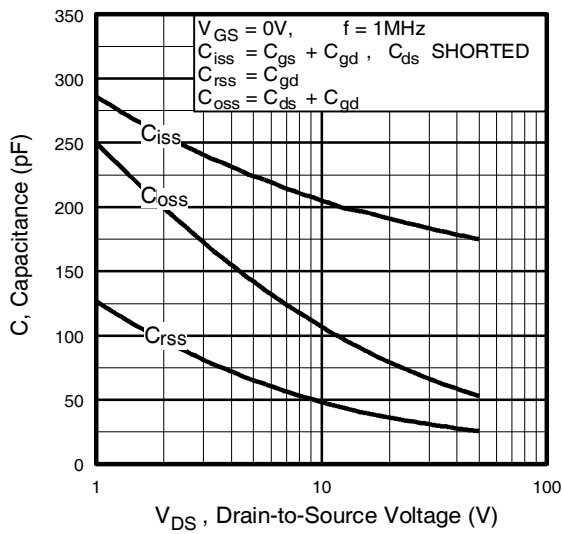


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

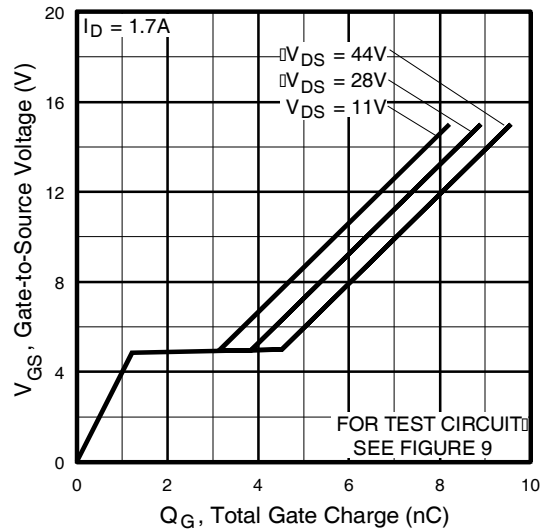


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

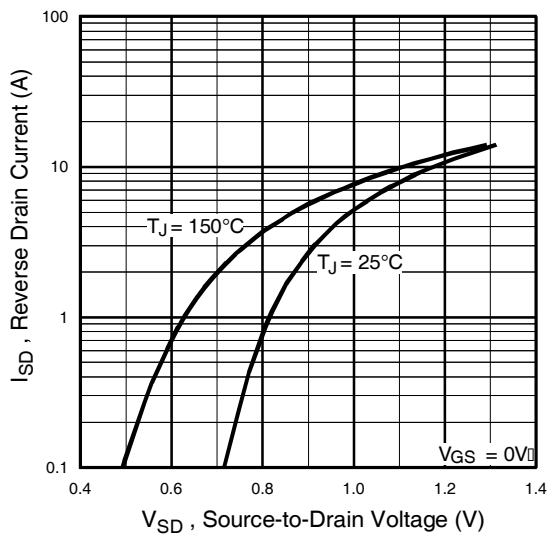


Fig 7. Typical Source-Drain Diode Forward Voltage

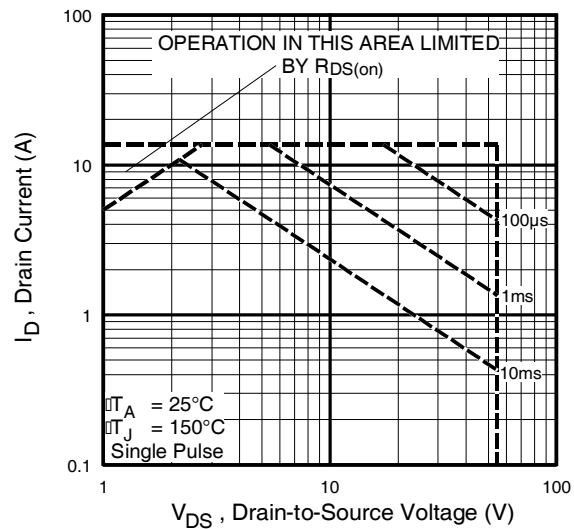


Fig 8. Maximum Safe Operating Area

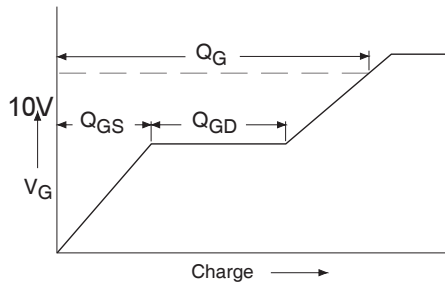


Fig 9a. Basic Gate Charge Waveform

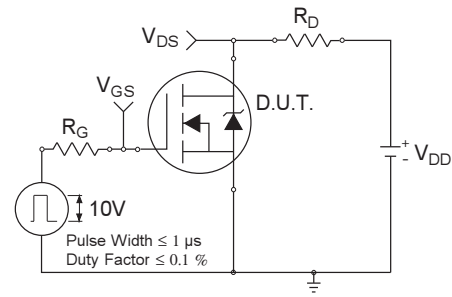


Fig 10a. Switching Time Test Circuit

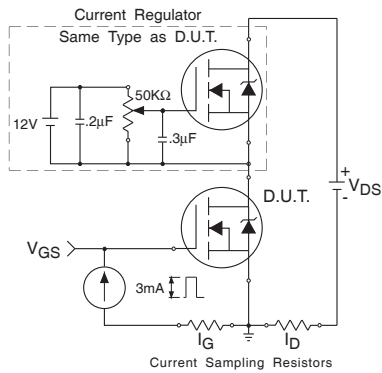


Fig 9b. Gate Charge Test Circuit

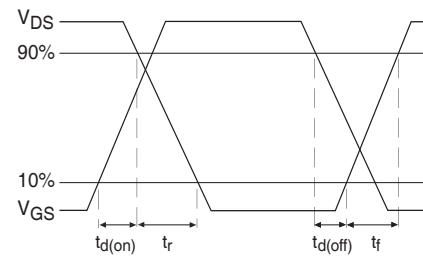


Fig 10b. Switching Time Waveforms

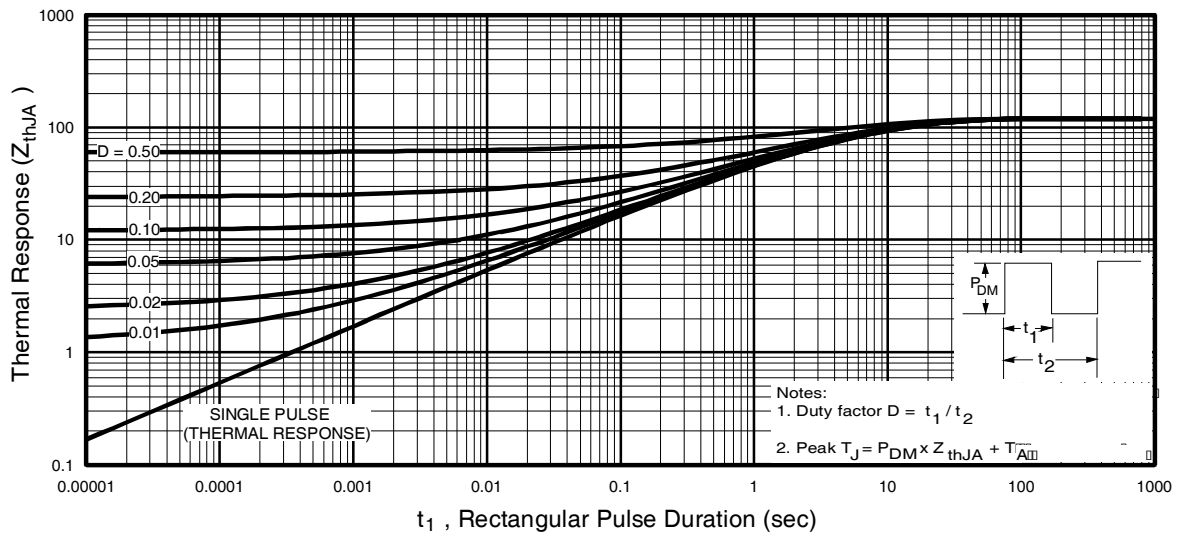


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

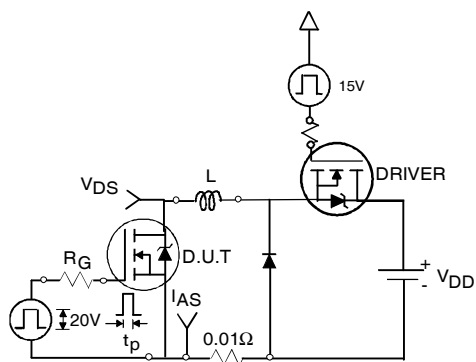


Fig 12a. Unclamped Inductive Test Circuit

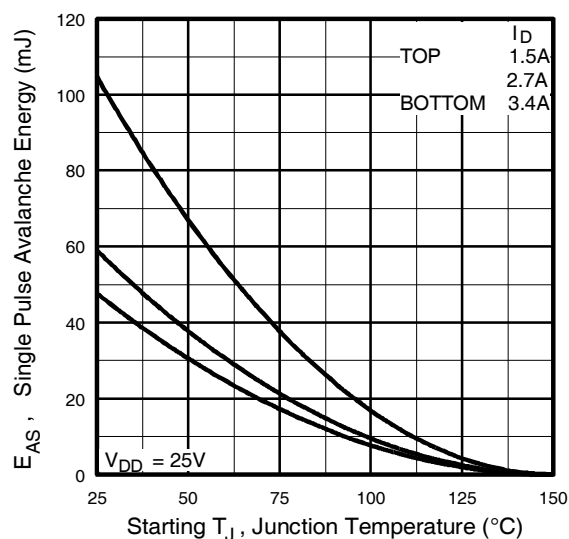


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

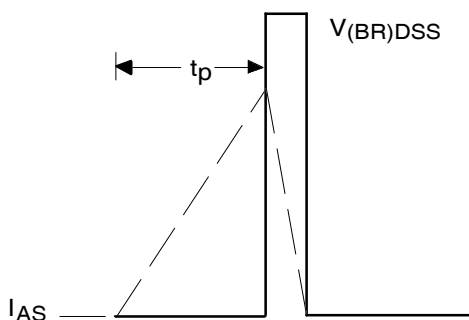
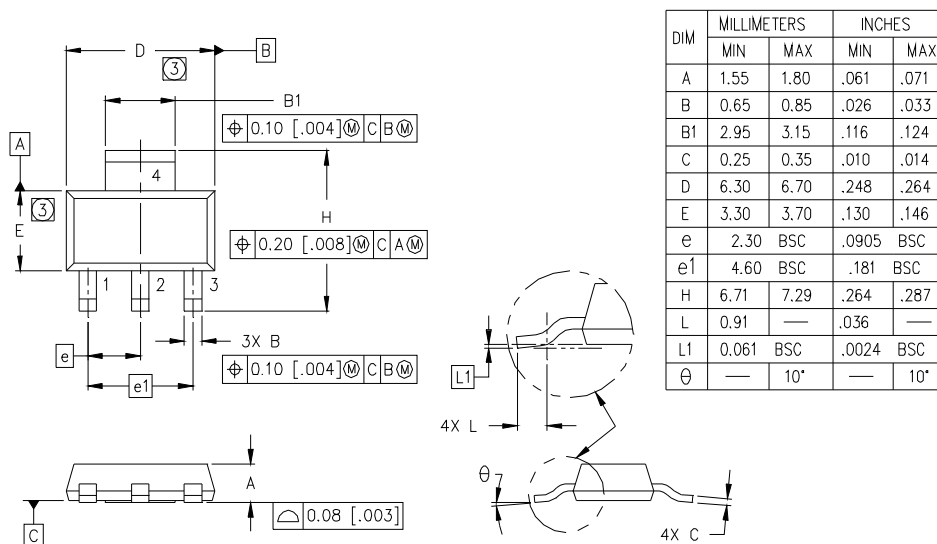


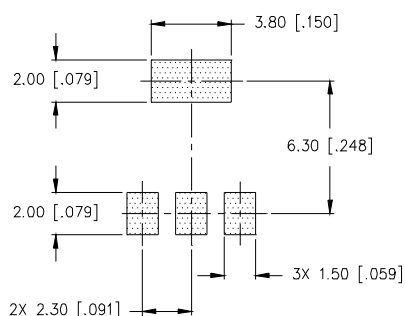
Fig 12b. Unclamped Inductive Waveforms

SOT-223 (TO-261AA) Package Outline

Dimensions are shown in millimeters (inches)



MINIMUM RECOMMENDED FOOTPRINT



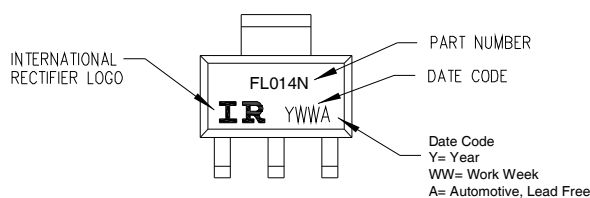
LEAD ASSIGNMENTS

- 1 = GATE
- 2 = DRAIN
- 3 = SOURCE
- 4 = DRAIN

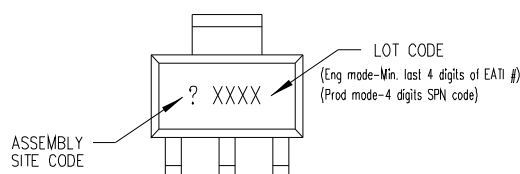
NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH.
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-261AA.
5. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

SOT-223 (TO-261AA) Part Marking Information



TOP MARKING

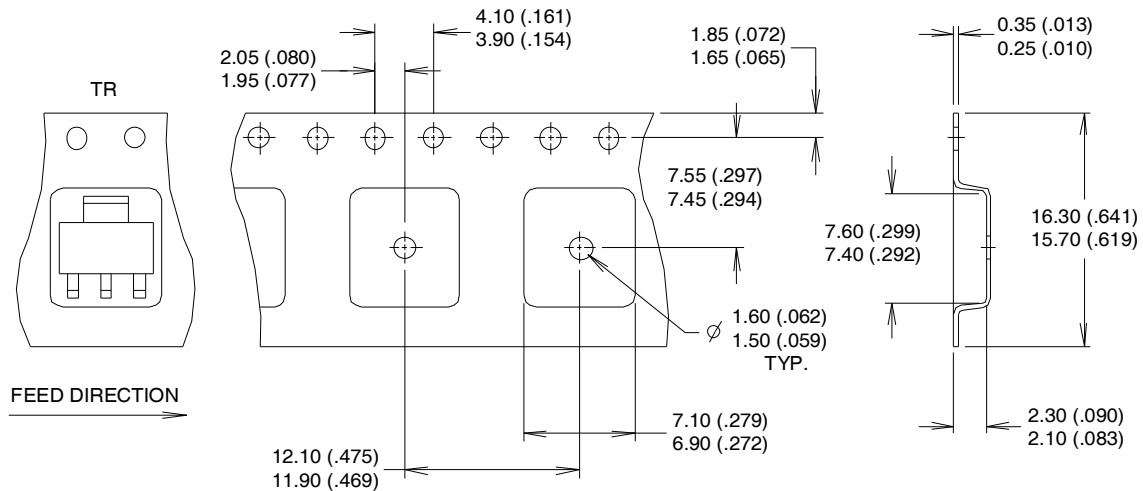


BOTTOM MARKING

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

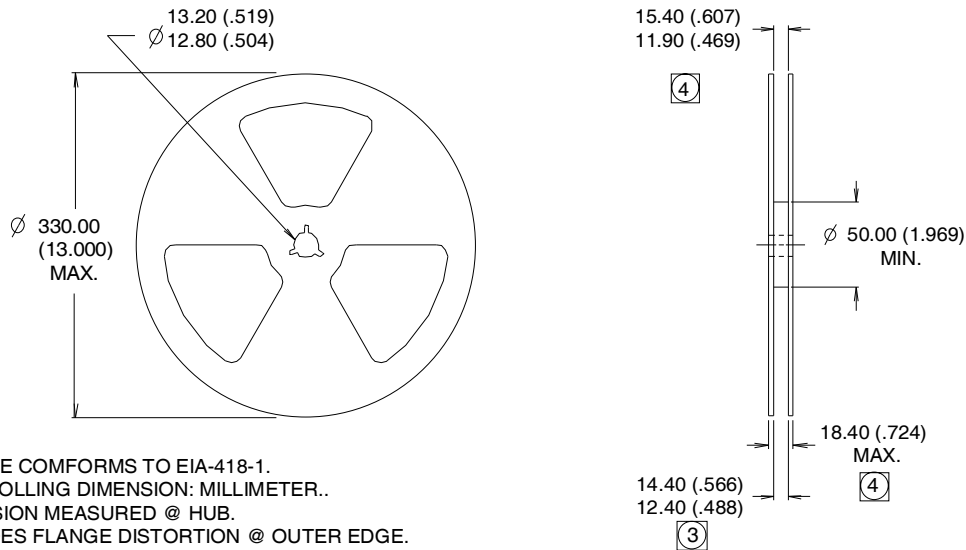
SOT-223 (TO-261AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :

1. CONTROLLING DIMENSION: MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.
3. EACH ϕ 330.00 (13.00) REEL CONTAINS 2,500 DEVICES.



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level		SOT-223	MSL1
ESD	Machine Model	Class M1A(+/- 50V) ^{†††} (per AEC-Q101-002)	
	Human Body Model	Class H1A(+/- 350V) ^{†††} (per AEC-Q101-001)	
	Charged Device Model	Class C5(+/- 2000V) ^{†††} (per AEC-Q101-005)	
RoHS Compliant		Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.

^{†††} Highest passing voltage

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<http://www.irf.com/technical-info/>

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Tel: (310) 252-7105

Revision History

Date	Comments
3/26/2014	<ul style="list-style-type: none"> • Updated part marking on page 7 • Updated data sheet with new IR corporate template